



# Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Pavilion HPE h9 Phoenix PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB, PSU PCA, Graphic card PCA	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	The quantity may vary from different power supply (PSU) models	8
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	system fan, cooler fan, PSU fan	3
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
screw driver	
wire cutters/clippers	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel from the unit
2. Take off the front bezel from the unit.
3. Remove top bezel from the unit.
4. Remove all the cables from PCA.
5. Remove HDD from the unit.
6. Remove ODD from the unit.
7. Remove CPU cooler from PCA,
8. Remove system fan from the unit.
9. Take off Memory and graphic card.
10. Take off front IO connector box from the unit.
11. Take off Top IO connector box from the unit.
12. Take off PSU from the Unit
13. Remove the Electrolytic capacitors from the PSU (up to 8)
14. Take off PCA from the Unit.
15. Take off CMOS battery

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



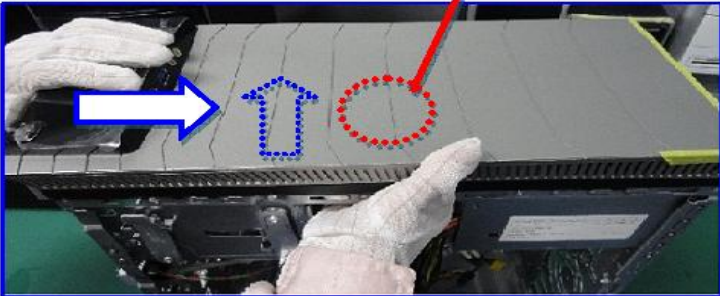
**1.Remove access panel from the unit**

Release thumb screw on the access panel, pull towards the rear and remove it from unit.



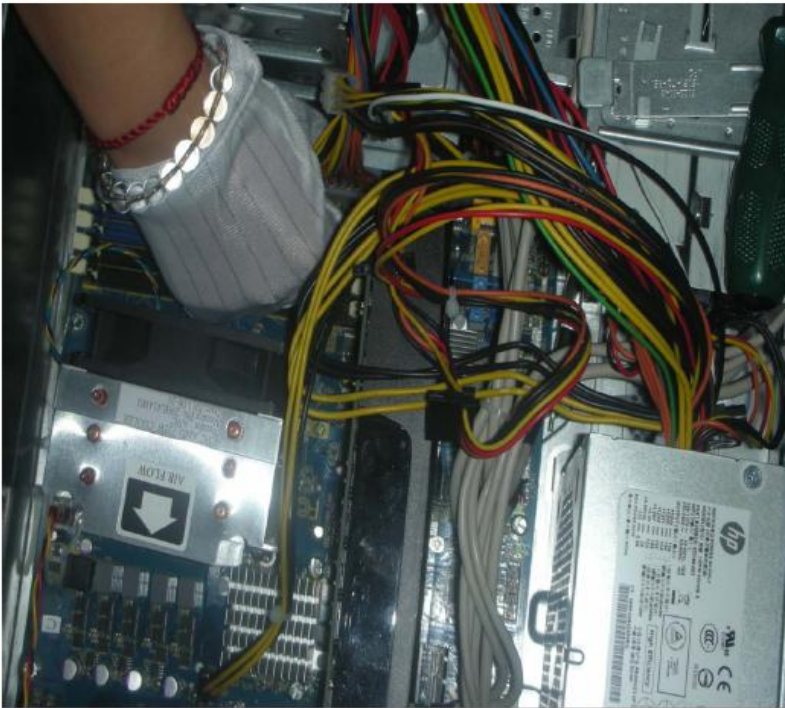
**2 Take off the front bezel from the unit.**

Release 3 bezel latches from chassis by pulling outwards of the bezel latches.

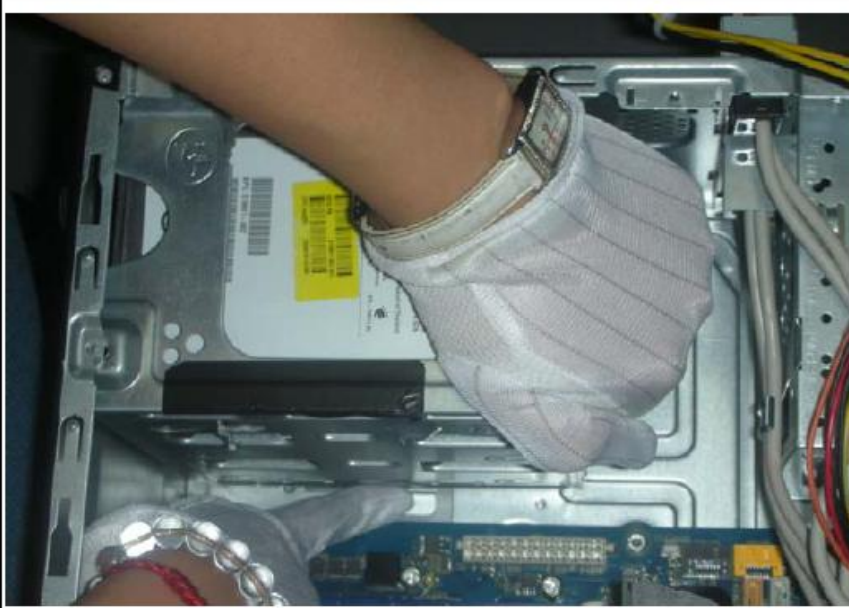


**3.Remove top bezel from the unit.**

Press the latch on the back and push top bezel as the arrow shown, then remove the bezel from unit.



**4 Remove all the cables from PCA.**



5.Remove HDD from the unit.





6. Remove ODD from the unit.





7 Remove CPU cooler from PCA



8.Remove system fan from the unit.



**9 Take off Memory and graphic card**

Release memory socket levers by pulling outward

Release graphic card from the slot.





**10. Take off FIO from the unit**

Use screw driver to loose screws and then take the FIO off the Unit



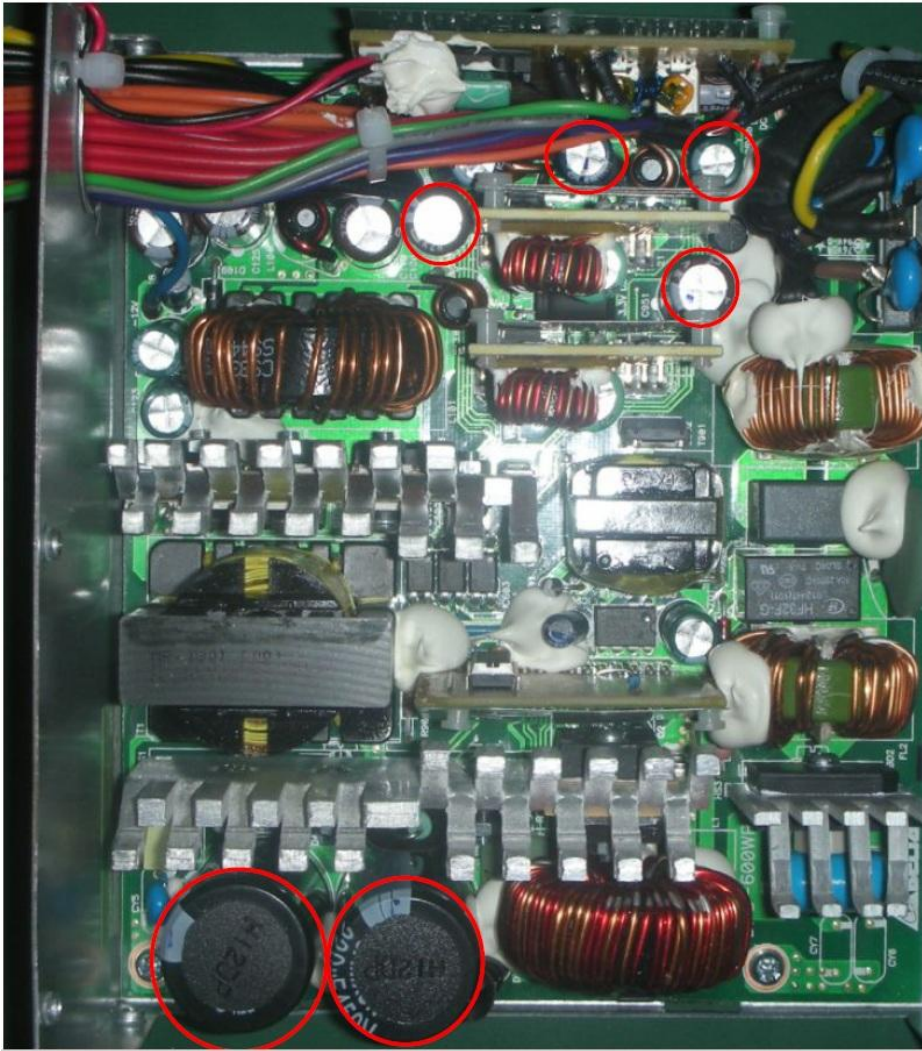
**11. Take off Top IO from the unit.**



**12 Take off PSU from the Unit**

Use screw driver to loose screws and then take the PSU off the Unit

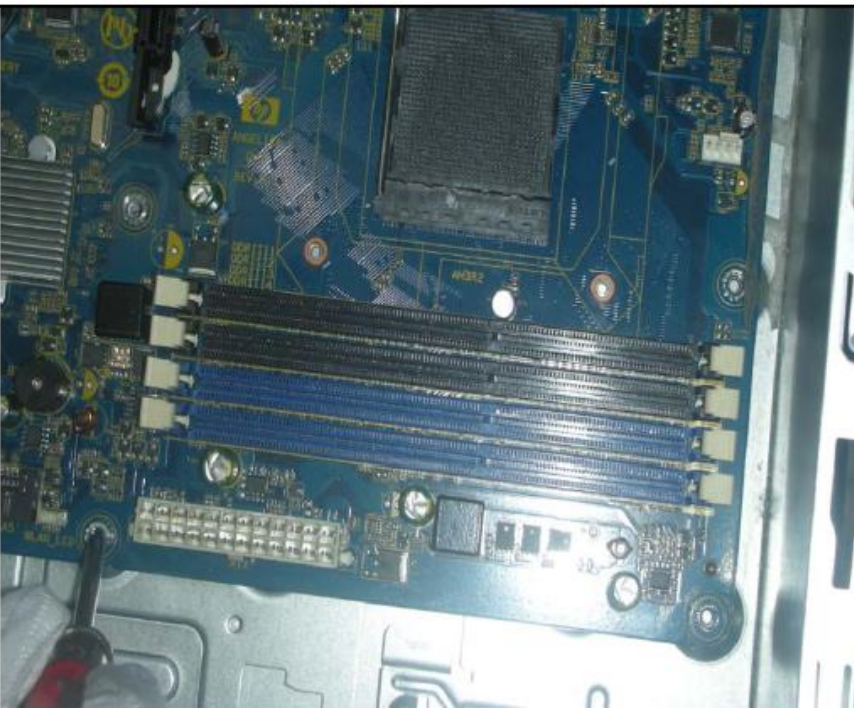
Remove the power supply (PSU) cover and remove the electrolytic capacitors from the power supply (PSU) – up to 8 by cutting them off from the PCA with clippers at the solder/pin connection point.





### 13. Take off CMOS battery

Pull the battery holder as shown in the photo, and then the battery will off the PCA



### 14. Take off PCA from the Unit

Use screw driver to loose screws and then take the PCA off the Unit